

SEMiX604GB12Vs



SEMiX® 4s

SEMiX604GB12Vs

Features

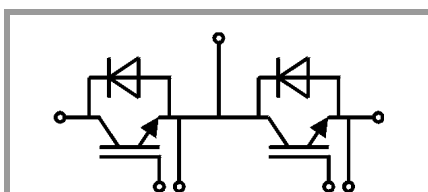
- Homogeneous Si
- $V_{CE(sat)}$ with positive temperature coefficient
- High short circuit capability
- UL recognised file no. E63532

Typical Applications*

- AC inverter drives
- UPS
- Electronic Welding

Remarks

- Case temperature limited to $T_C=125^{\circ}\text{C}$ max.
- Product reliability results are valid for $T_J=150^{\circ}\text{C}$
- Dynamic values apply to the following combination of resistors:
 $R_{Gon,main} = 1,0\ \Omega$
 $R_{Goff,main} = 1,0\ \Omega$
 $R_{G,X} = 2,2\ \Omega$
 $R_{E,X} = 0,5\ \Omega$



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Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
IGBT				
V _{CES}			1200	V
I _C	T _j = 175 °C	T _c = 25 °C	880	A
		T _c = 80 °C	670	A
I _{Cnom}			600	A
I _{CRM}	I _{CRM} = 3xI _{Cnom}		1800	A
V _{GES}			-20 ... 20	V
t _{psc}	V _{CC} = 600 V V _{GE} ≤ 15 V V _{CES} ≤ 1200 V	T _j = 125 °C	10	μs
T _j			-40 ... 175	°C
Inverse diode				
I _F	T _j = 175 °C	T _c = 25 °C	707	A
		T _c = 80 °C	529	A
I _{Fnom}			600	A
I _{FRM}	I _{FRM} = 3xI _{Fnom}		1800	A
I _{FSM}	t _p = 10 ms, sin 180°, T _j = 25 °C		3240	A
T _j			-40 ... 175	°C
Module				
I _{t(RMS)}	T _{terminal} = 80 °C		600	A
T _{stg}			-40 ... 125	°C
V _{isol}	AC sinus 50Hz, t = 1 min		4000	V

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
IGBT						
V _{CE(sat)}	I _C = 600 A	T _j = 25 °C		1.75	2.2	V
	V _{GE} = 15 V chipelevel	T _j = 150 °C		2.2	2.5	V
V _{CE0}		T _j = 25 °C		0.94	1.04	V
		T _j = 150 °C		0.88	0.98	V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C		1.4	1.9	mΩ
		T _j = 150 °C		2.2	2.5	mΩ
V _{GE(th)}	V _{GE} =V _{CE} , I _C = 24 mA		5.5	6	6.5	V
I _{CES}	V _{GE} = 0 V	T _j = 25 °C		0.1	0.3	mA
	V _{CE} = 1200 V	T _j = 150 °C				mA
C _{ies}	V _{CE} = 25 V V _{GE} = 0 V	f = 1 MHz		36.0		nF
C _{oes}		f = 1 MHz		3.55		nF
C _{res}		f = 1 MHz		3.54		nF
Q _G	V _{GE} = - 8 V...+ 15 V			6600		nC
R _{Gint}	T _j = 25 °C			1.25		Ω
t _{d(on)}	V _{CC} = 600 V	T _j = 150 °C		517		ns
t _r	I _C = 600 A			94		ns
E _{on}	V _{GE} = ±15 V	T _j = 150 °C		58.7		mJ
t _{d(off)}	R _{G on} = 1.7 Ω	T _j = 150 °C		788		ns
t _f	R _{G off} = 1.7 Ω	T _j = 150 °C		102		ns
E _{off}	di/dt _{on} = 6300 A/μs	T _j = 150 °C		78.5		mJ
	di/dt _{off} = 5400 A/μs					
	du/dt _{off} = 6800 V/μs					
R _{th(j-c)}	per IGBT				0.051	K/W

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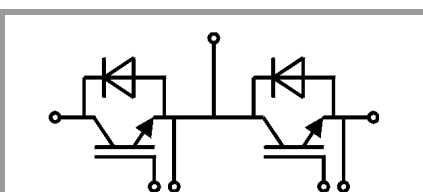
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Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
Inverse diode						
V _F = V _{EC}	I _F = 600 A V _{GE} = 0 V chip	T _j = 25 °C		2.1	2.46	V
		T _j = 150 °C		2.1	2.4	V
V _{F0}		T _j = 25 °C	1.1	1.3	1.5	V
		T _j = 150 °C	0.7	0.9	1.1	V
r _F		T _j = 25 °C	1.1	1.4	1.6	mΩ
		T _j = 150 °C	1.8	1.9	2.1	mΩ
I _{RRM}	I _F = 600 A	T _j = 150 °C		463		A
Q _{rr}	di/dt _{off} = 6200 A/μs	T _j = 150 °C		110		μC
E _{rr}	V _{GE} = -15 V V _{CC} = 600 V	T _j = 150 °C		49.5		mJ
R _{th(j-c)}	per diode				0.086	K/W
Module						
L _{CE}				22		nH
R _{CC'+EE'}	res., terminal-chip	T _C = 25 °C		0.7		mΩ
		T _C = 125 °C		1		mΩ
R _{th(c-s)}	per module			0.03		K/W
M _s	to heat sink (M5)		3		5	Nm
M _t		to terminals (M6)	2.5		5	Nm
						Nm
w					400	g
Temperatur Sensor						
R ₁₀₀	T _C =100°C (R ₂₅ =5 kΩ)			493 ± 5%		Ω
B _{100/125}	R _(T) =R ₁₀₀ exp[B _{100/125} (1/T-1/T ₁₀₀)]; T[K];			3550 ±2%		K



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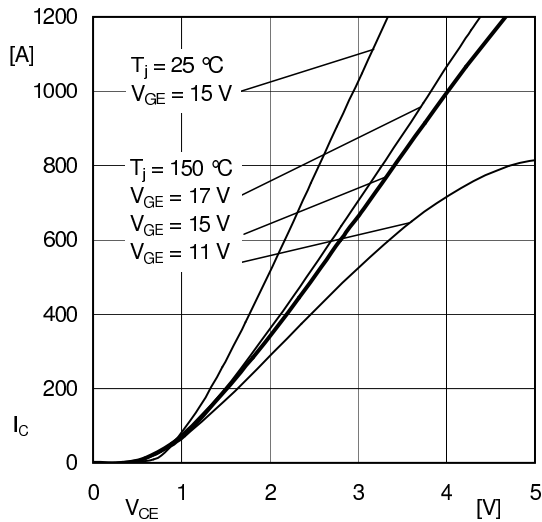


Fig. 1: Typ. output characteristic, inclusive $R_{CC'} + EE'$

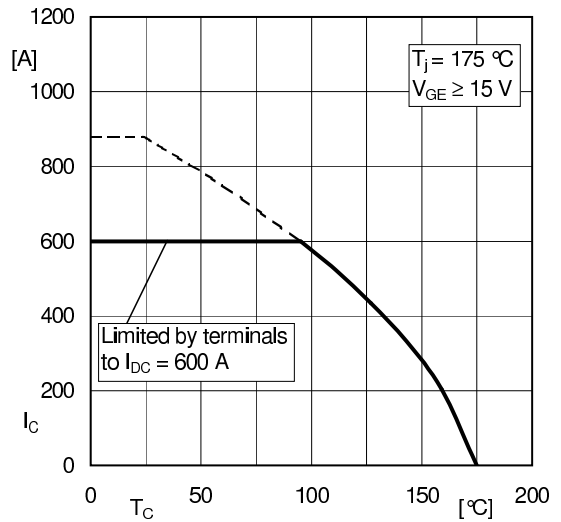


Fig. 2: Rated current vs. temperature $I_C = f(T_C)$

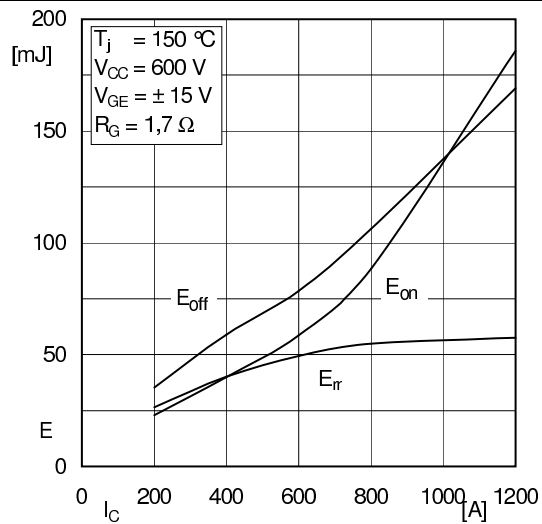


Fig. 3: Typ. turn-on /-off energy = $f(I_C)$

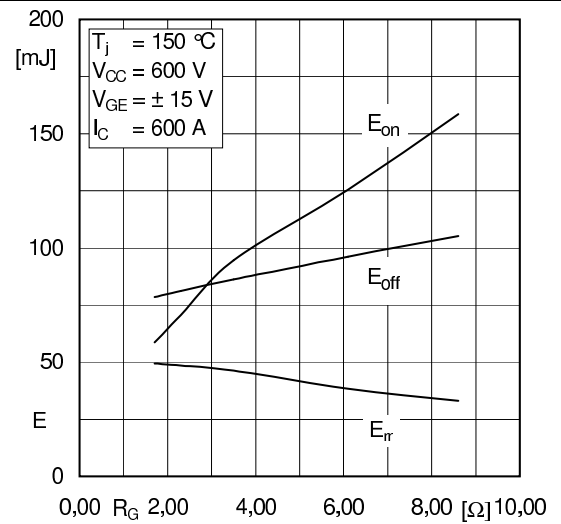


Fig. 4: Typ. turn-on /-off energy = $f(R_G)$

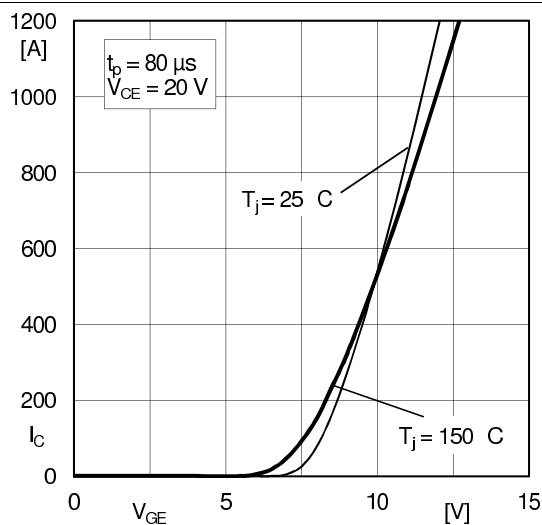


Fig. 5: Typ. transfer characteristic

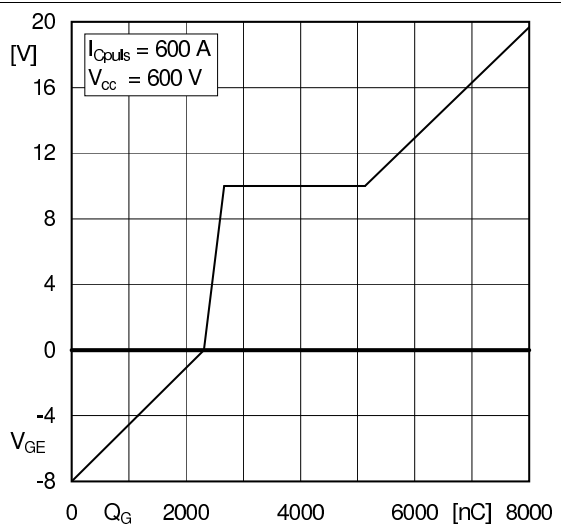


Fig. 6: Typ. gate charge characteristic

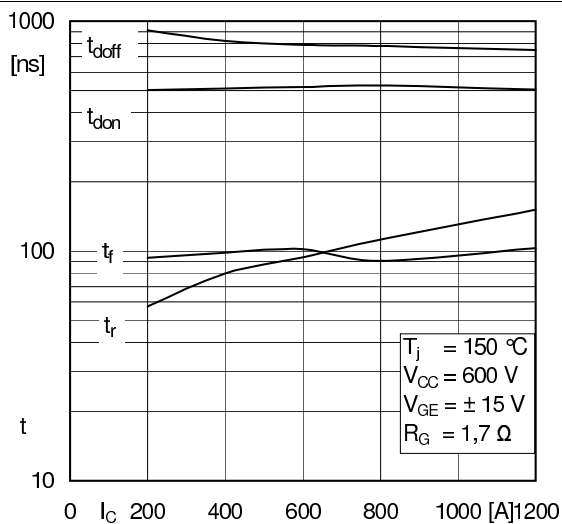


Fig. 7: Typ. switching times vs. I_C

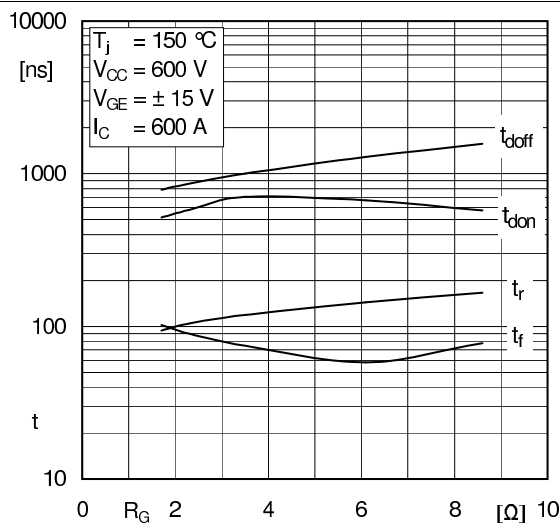


Fig. 8: Typ. switching times vs. gate resistor R_G

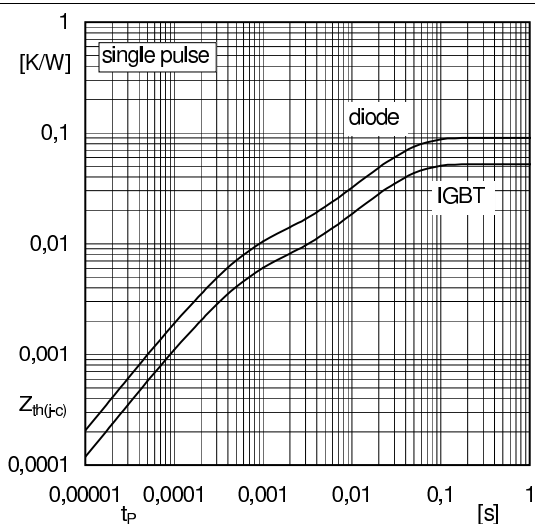


Fig. 9: Typ. transient thermal impedance

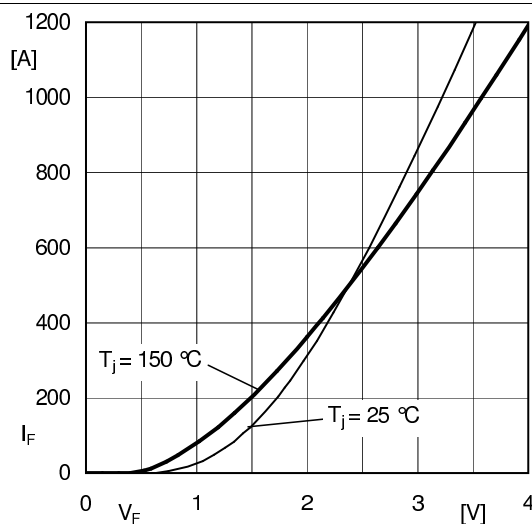


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC'+EE'}$

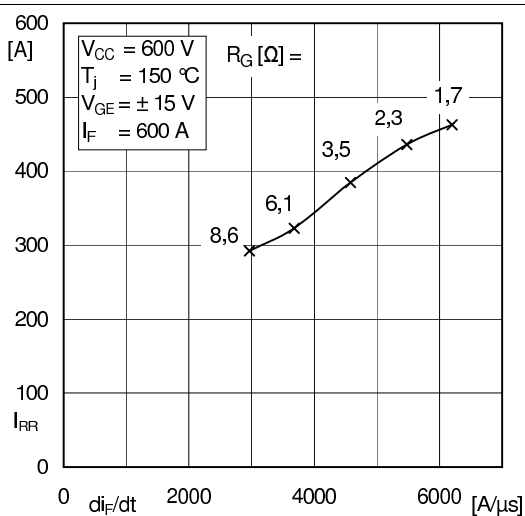


Fig. 11: Typ. CAL diode peak reverse recovery current

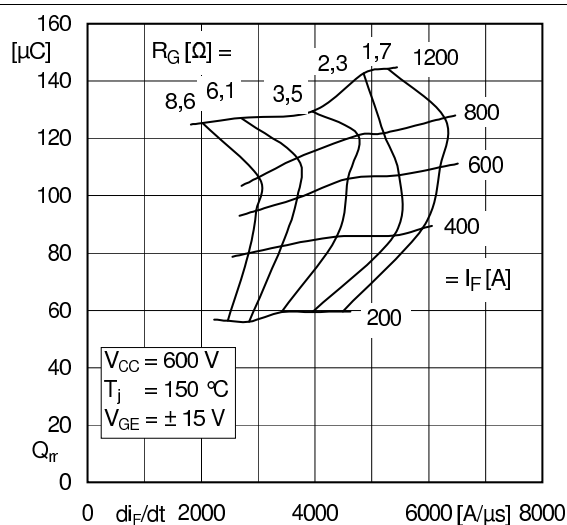
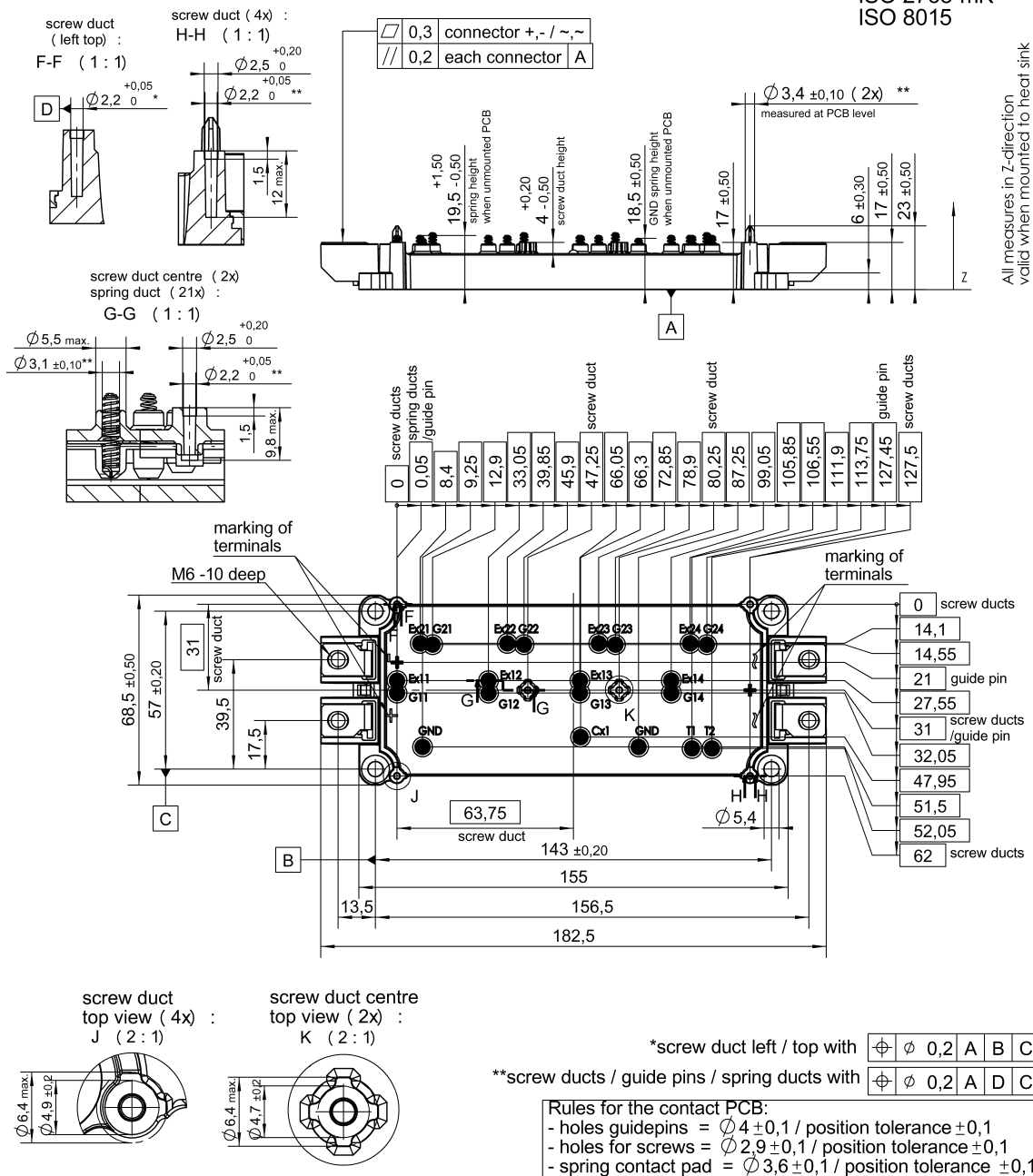


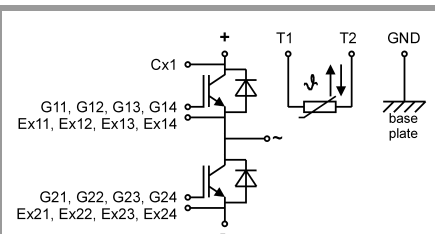
Fig. 12: Typ. CAL diode recovery charge

Case: SEMiX 4s

general tolerance:
ISO 2768-mK
ISO 8015



SEMiX 4s



spring configuration

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.